

[Document] Abstract

[Summary]

[Problems] Provision of a polyimide film superior in heat resistance, rigidity and high frequency property, 5 which is free of inconveniences due to curling even when various functional layers are laminated with heating, and which is preferable as a substrate film superior in thermal degradation stability for electronic parts.

[Solving Means] A polyimide film having a planar 10 orientation coefficient of 0.79-0.89 as measured by an X-ray diffraction method, a difference in the surface planar orientation degree between one surface thereof and the other surface thereof of not more than 2 and a curling degree of not more than 5%, which is obtained by 15 imidation of a polyimide precursor film having a particular imidation rate.

[Main Drawing] None